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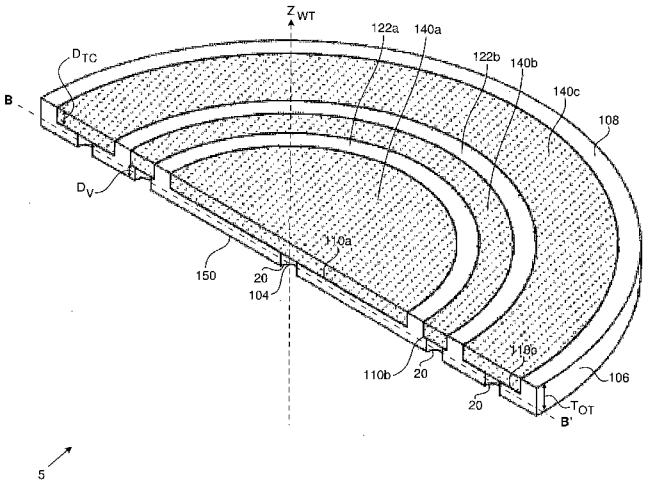
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(54) Title: SINGLE ULTRA-PLANAR WAFER TABLE STRUCTURE FOR BOTH WAFERS AND FILM FRAMES



(57) Abstract: A wafer table structure providing a single wafer table surface suitable for handling both wafers and film frames includes a base tray having a set of compartments formed therein by way of a set of ridges formed in or on an interior base tray surface; a hardenable fluid permeable compartment material disposed within the set of base tray compartments; and a set of openings formed in the base tray interior surface by which the hardened compartment material is exposable to negative or positive pressures. The base tray includes a first ceramic material (e.g., porcelain), and the hardenable compartment material includes a second ceramic material. The base tray and the compartment material are simultaneously machinable by way of a standard machining process to thereby planarize exposed outer surfaces of the base tray and the hardened compartment material at an essentially identical rate for forming a highly or ultra-planar wafer table surface.

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